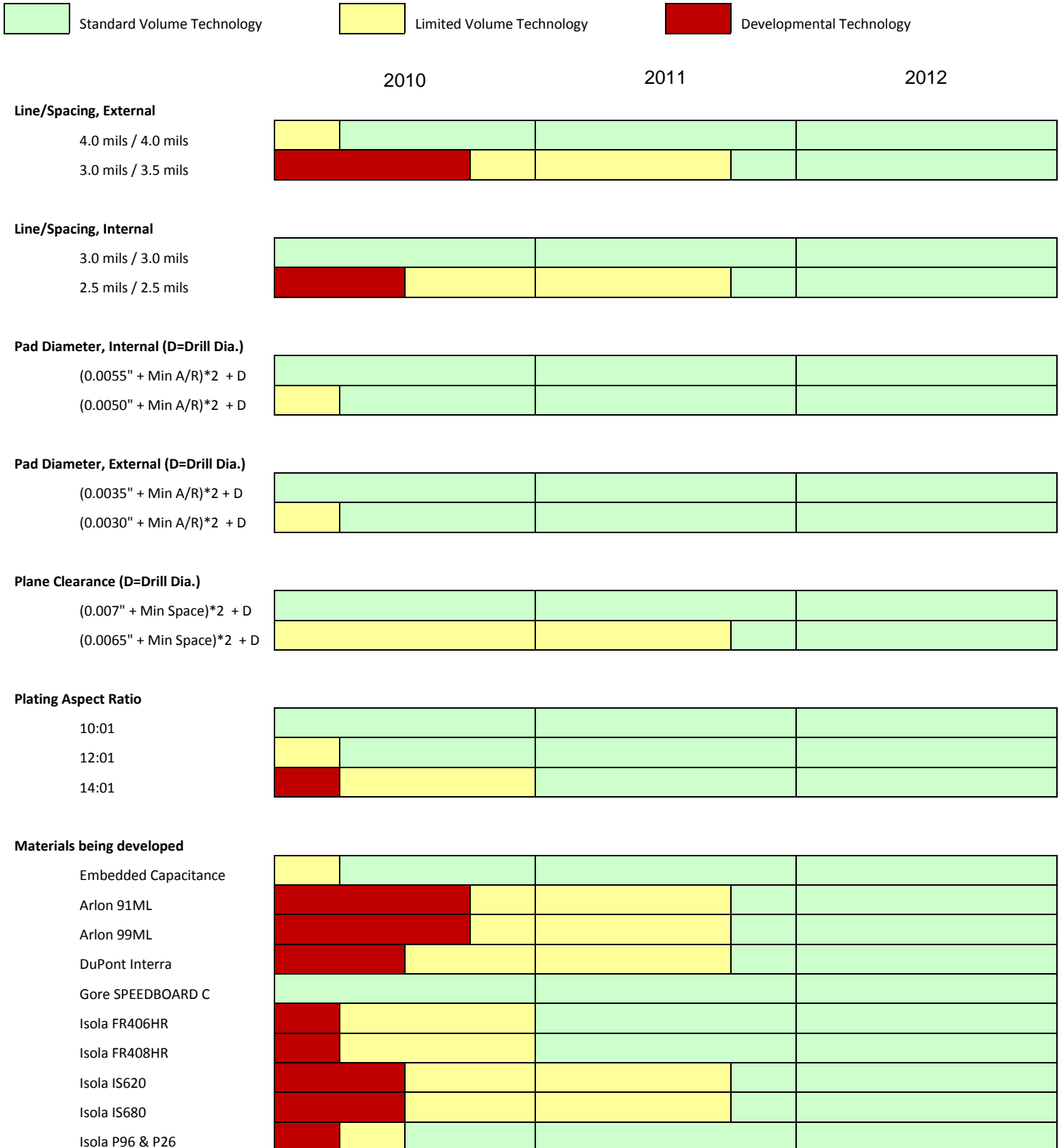


Technology Road Map



Micro Foils (8 microns)
 Ohmega Ohmega-Ply
 Rogers LCP
 Zeta Lam

Laser uVias

.9:1 aspect ratio
 .003 Dia
 .007" Capture Pad Dia (Outer)
 .007" Target Pad Dia (Inner)
 Staggered
 Stacked > 4 High
 Cu uVia Fill
 260C Tg Non-conductive uVia Fill
 Non-conductive uVia Fill

Surface Finish

Hot Air Solder Level (HASL)
 Electroless Ni Imm. Gold (ENIG)
 Hot Oil Reflow
 IR Fused
 Selective Solder Strip
 Electrolytic Ni/Gold
 Electrolytic Hard Ni
 Carbon Ink
 Selective Finishes
 Electroless Bondable Soft Au
 Electrolytic Gold (Soft)
 OSP
 Immersion Silver
 Lead Free HASL

Solder Masks

LPI
 Dry Film
 Screened
 LDI

Certifications

ISO 9000:200

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